



SM-G955F_REV0.5_A_F

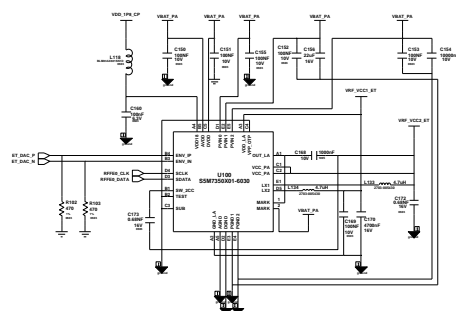
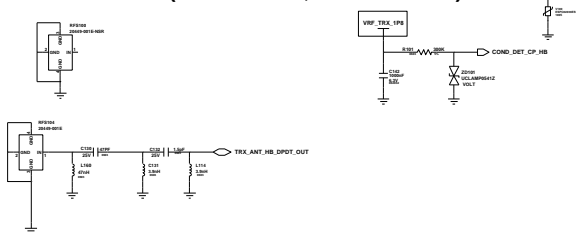
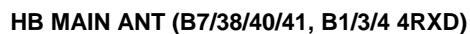
2017.02.02

- sheet01 : RF (1/2)
- sheet02 : RF (2/2)
- sheet03 : CP, TRANSCEIVER, MEMORY
- sheet04 : SENSORS, HUB, BT/WIFI, NFC, GPS, FM, BTP
- sheet05 : EXYNOS8895, SIM SOCKET
- sheet06 : EXYNOS8895
- sheet07 : POWER(PMIC), IF PMIC, WPC, MST
- sheet08 : AUDIO CODEC, SUB PCB
- sheet09 : DISPLAY, CAMERA
- sheet10 : IRIS CAM, DUAL CAM

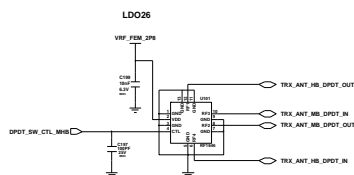
Project	
Sheet No	
Rev	
Rev Date	Rev Date
Rev Desc	Rev Desc
Rev Date	Rev Date
Rev Desc	Rev Desc
Rev Date	Rev Date
Rev Desc	Rev Desc

RF1 - MAIN ANT

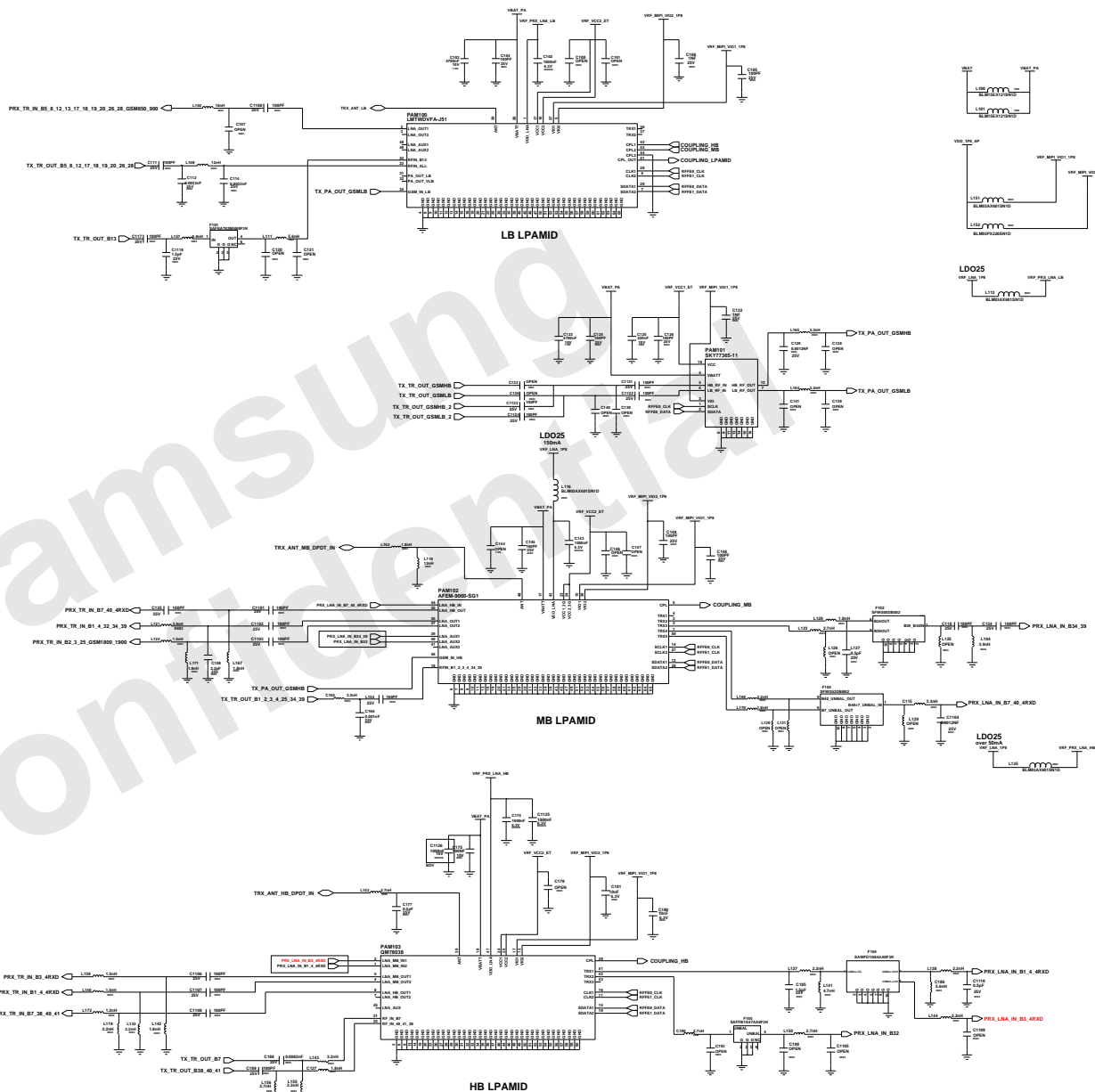
(B1/2/3/4/5/8/12/13/17/18/19/20/25/26/28/34/39,
B7/40 4RXD)



S735 ET MODULATOR

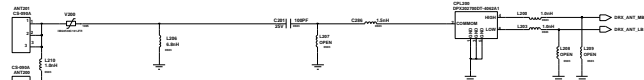


MB/HB SWITCH(DPDT)

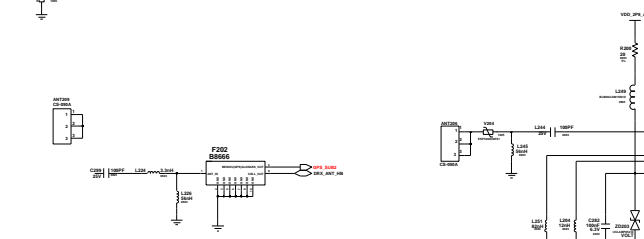


Engineer:			
DATE:			
Drawn by:			
DATE:			
REV:			
PROJ. NO.:	TITLE:		
DESIGNER:			
CHECKED:			
APPROVED:			
DATE:			
REV:			

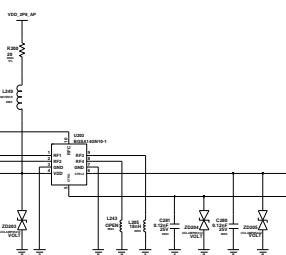
RF2



LB/MB SUB ANT



HB SUB ANT



ANT SWITCH

LD023

LD022

LD024

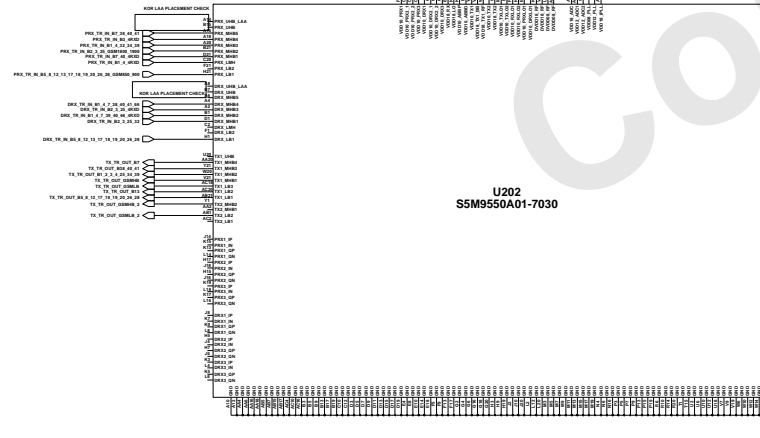
LD03

LD015

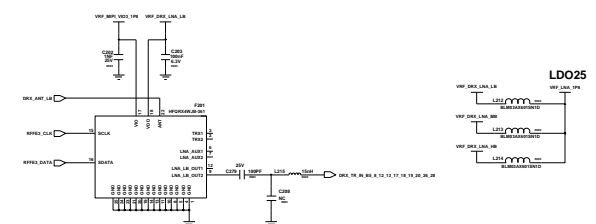
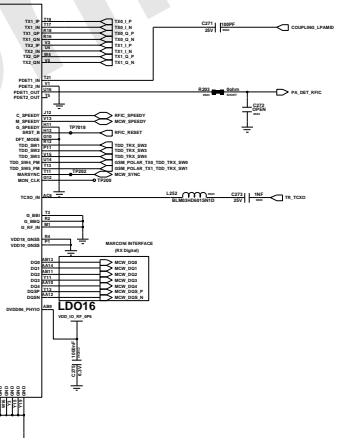
LD019

LD018

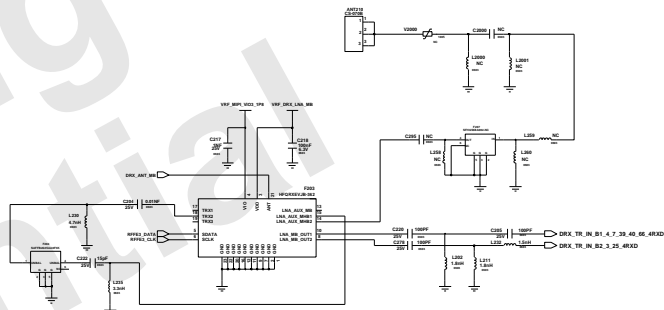
LD017



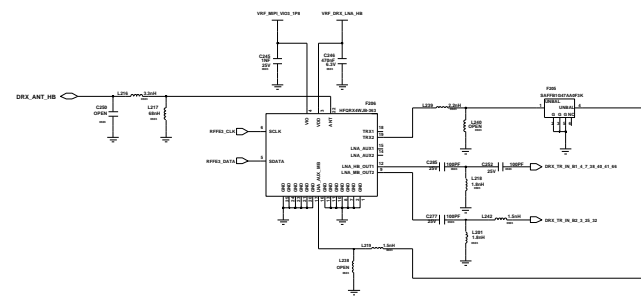
U202 SSM9550A01-7030



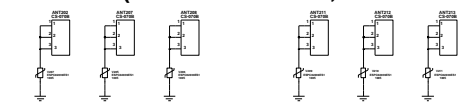
LB LFEM (B5/8/12/13/17/18/19/20/26/28)



MB LFEM (B1/4/39, B3/7/40 4RXD)



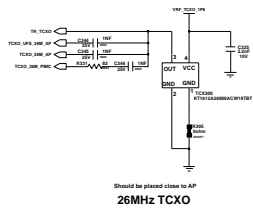
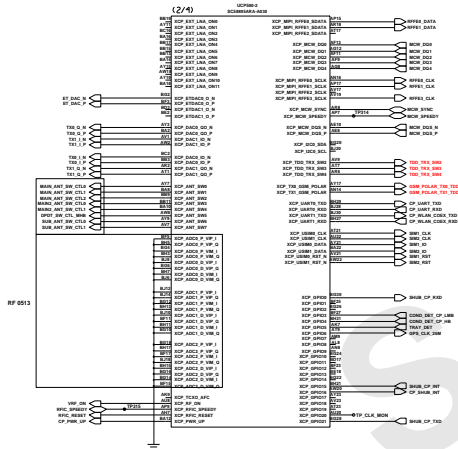
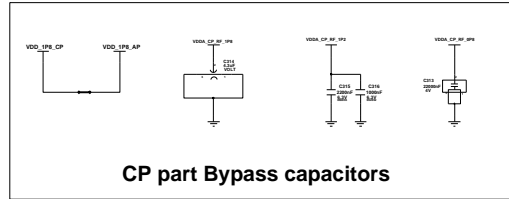
HB LFEM (B2/3/7/25/38/40/41, B1/4 4RXD)



GND_CONTACT

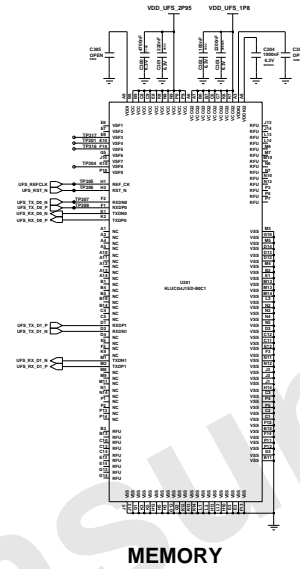
DREAM RF
101101

3. AP(EXTNOS8895) CP & UFS MEMORY

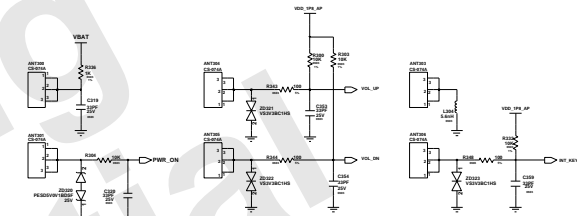


TCXO Buffer

THERMISTOR

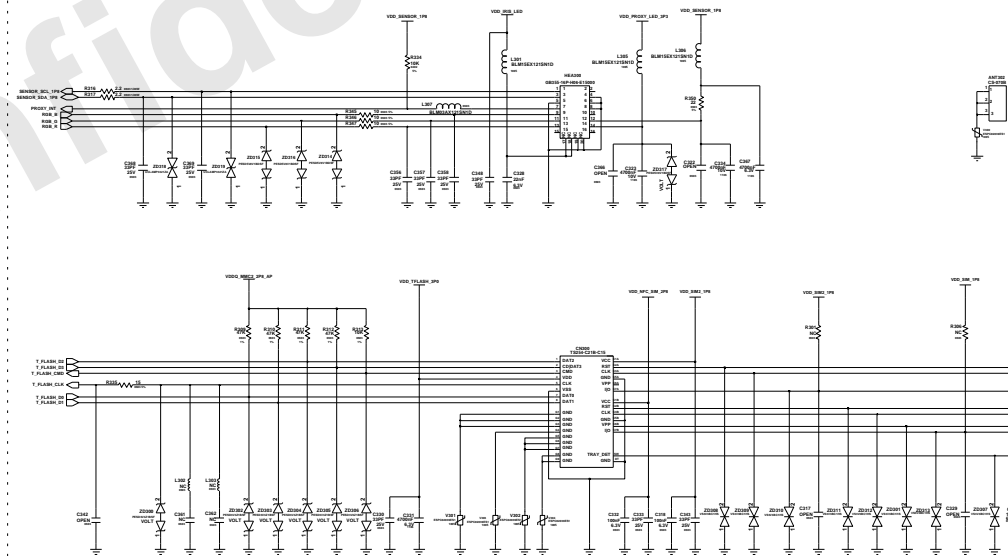


UFS BUCK BOOSTER



POWER / VOLUME KEY

T-FLASH / SIM / PROXY / IRIS LED / RGB



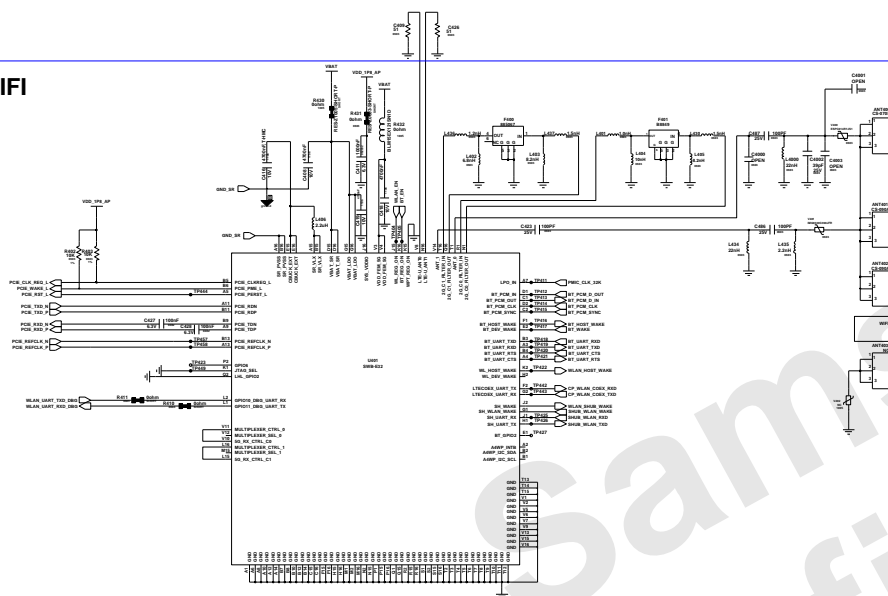
Project	CP & UFS MEMORY
File Name	DREAM2_KANGCHEN
File Path	...
File Size	...
File Date	...
File User	...

4. CONNECTIVITY / SENSOR

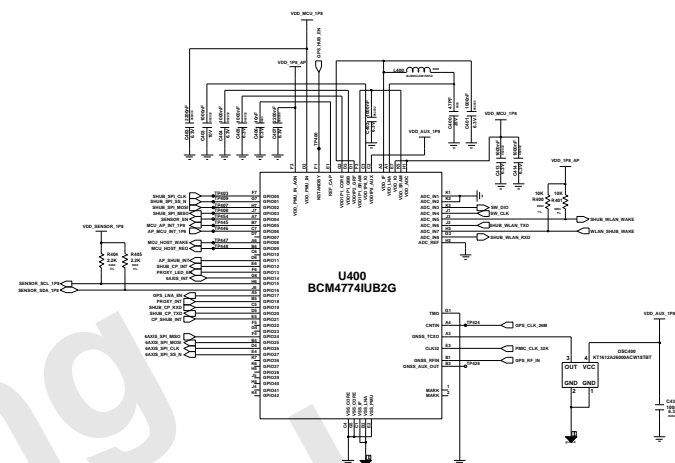
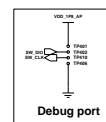
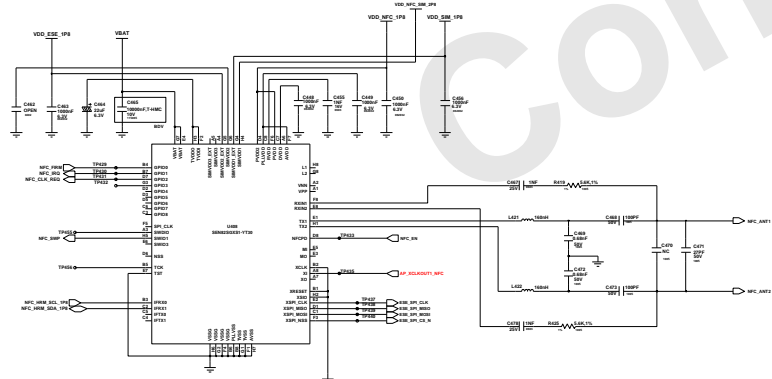
LAA
FOR KOR SKU

FOR KOR SKU

BT/WIFI

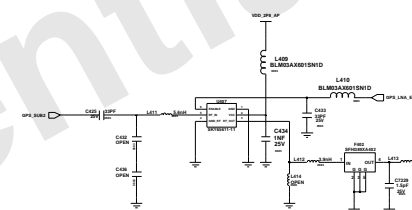


NFC

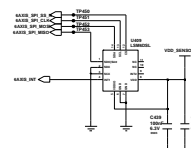


GPS + SENSOR HUB(BCM4774)

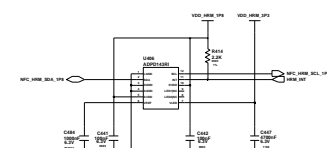
GPS



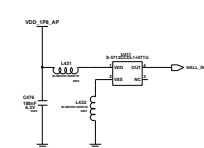
SENSORS



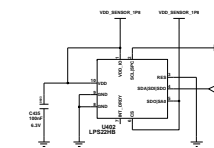
6 Axis Sensor (GYRO,ACCEL)



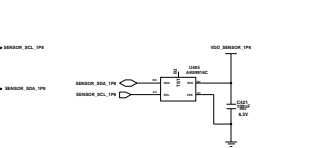
HRM Sensor



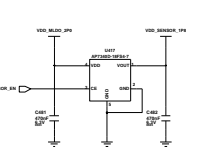
cover_detect Hall_IC



Barometer Sensor



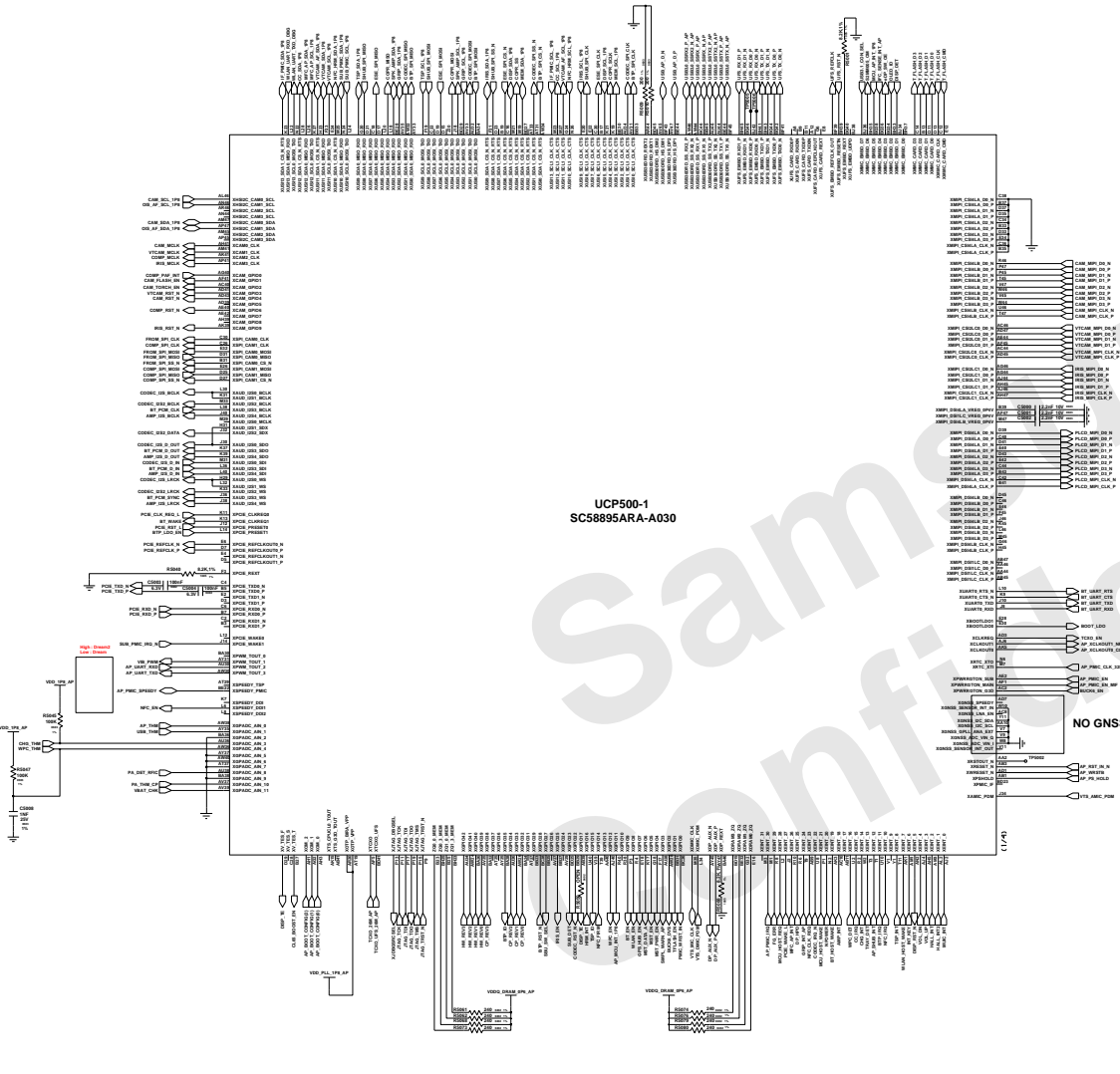
MAGNETIC SENSOR



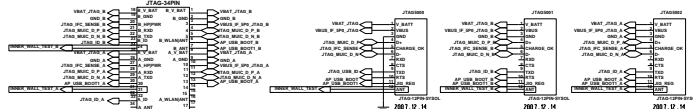
Engineer:	<div>CONNECTIVITY</div>				
Drawn by:					
Field Ckr:				TITLE:	Sheet AC
Doc Ctrk, Ckr:					
Info Engr Ckr:					
QA Ckr:	REV	Drawing Number:	Page		

5. EXYNOS8895(KANGCHEN) & ETC

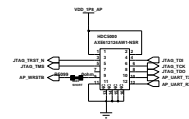
KANGCHEN_AP



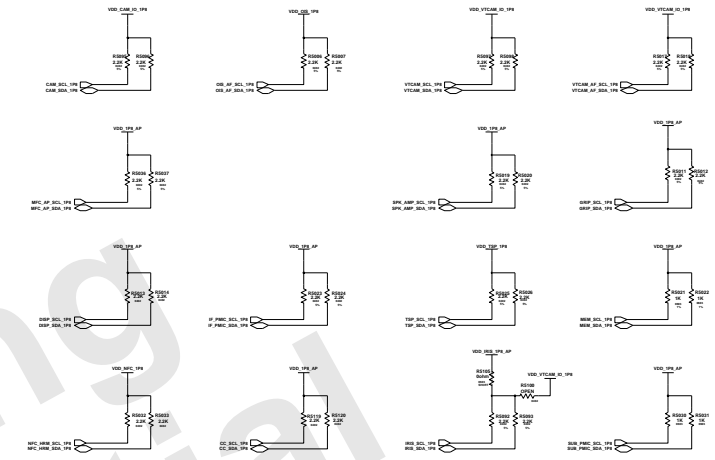
PCB JTAG



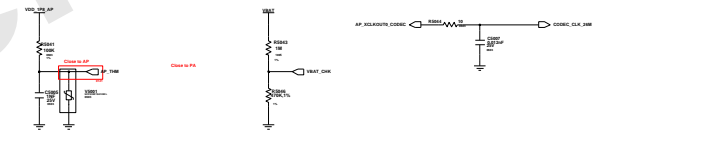
JTAG Connector



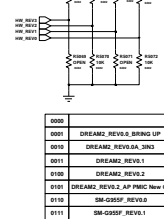
H/W I2C



ETC



1010

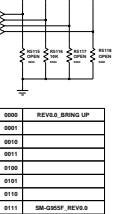


H/W Revision Setting

0000	144 / 2nd
0001	DREAM2_REV0.0.BRING UP
0010	UFS2_C0 / UFS0
0011	UFS0
0100	DREAM2_REV0.1
0101	SD CARD / UFS0
0110	DREAM2_REV0.2
0111	DREAM2_REV0.3 AP PRIC New CTR
1000	SM-G950F_REV0.0
1001	SM-G950F_REV0.1

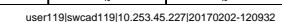
iROM BOOT

1011



CP H/W Revision Setting

0000	REV0.0.BRING UP
0001	
0010	
0011	
0100	
0101	
0110	
0111	SM-G950F_REV0.0

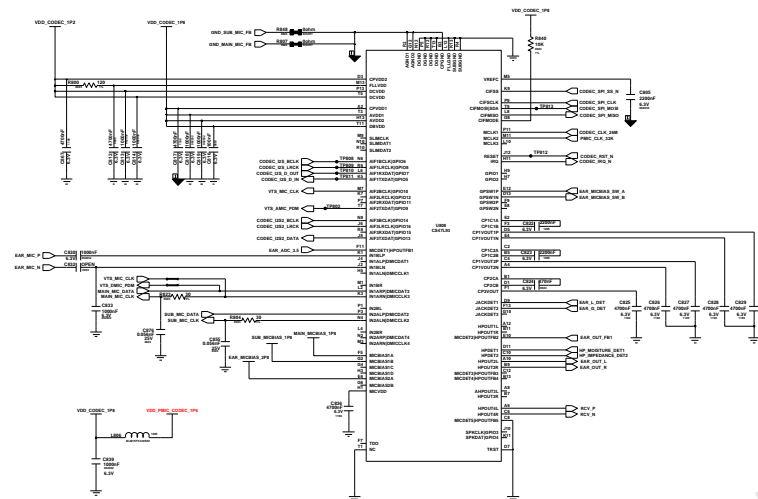




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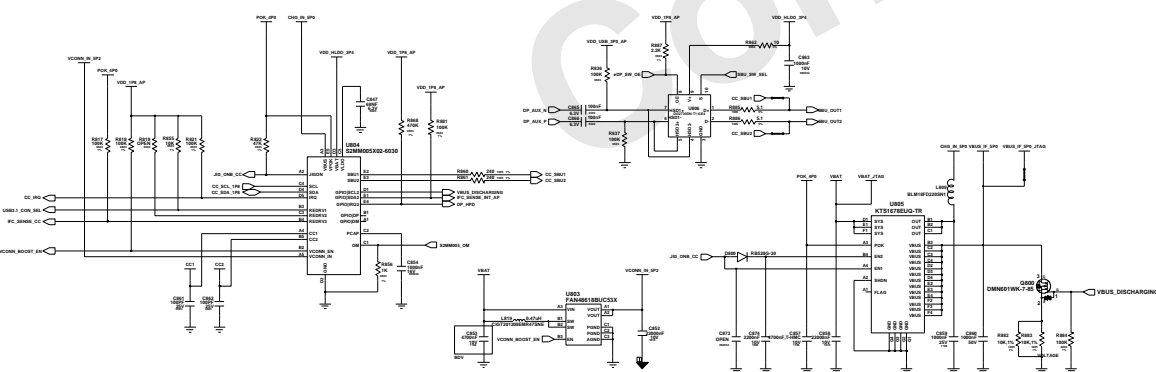

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AUDIO



AUDIO CODEC

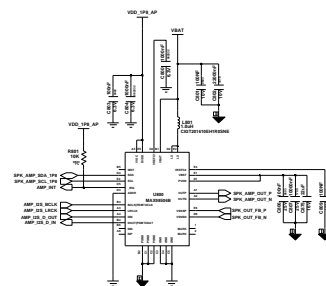
RCV CONTACT



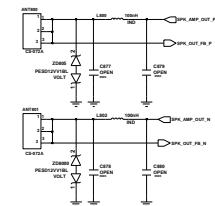
CC IC

USB TYPE-C

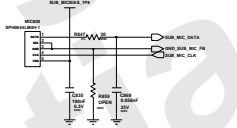
OVP LS



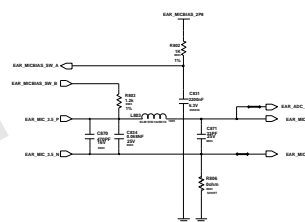
SPK AMP



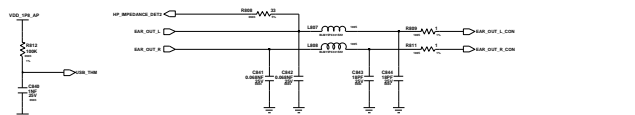
SPK CONTACT



SUB MIC



Ear MIC



LOWER SUB PCB CON.

Part No.	SAMSUNG
Rev.	1.0
Doc. No.	DREAM2_KANGCHEN
Rev. No.	1.0
Rev. Date	2010.10.10
Rev. By	1.0
Rev. Date	2010.10.10



	TSP_ID
0	ALPS
1	CRW

Engineer:	CAMERA, DISPLAY, MHL				
Drawn by:					
RAD CHK:				TITLE:	3
DOC CTRL CHK:				DREAM2_KANGCHEN	
MFG ENGR CHK:					
QA CHK:	REV	Drawing Number:	3		

